



15u

PATENT  
25611-000085/US

IN THE U.S. PATENT AND TRADEMARK OFFICE

APPLICANTS: Heung-Kyu KWON et al. CONF. NO.: 7367  
SERIAL NO.: 09/464,322 GROUP: 2815  
FILED: December 15, 1999 EXAMINER: C. Chu  
FOR: SEMICONDUCTOR CHIP PACKAGE AND METHOD OF FABRICATING  
THE SAME  
DOCKET NO.: 25611-000085/US

**STATUS INQUIRY**

Customer Service Window  
Randolph Building  
401 Dulany Street  
Alexandria, VA 22314

December 27, 2005

Sir:

Please advise the undersigned as to the status of the above-identified application as follows:

A duplicate copy of the present Status Inquiry is attached hereto. It is respectfully requested that the duplicate copy be marked appropriately to indicate the status of the above-identified application and returned to the undersigned as soon as possible.

Please call the undersigned, at 703-668-8000 if there are any questions with regard to the present request.

Respectfully submitted,

HARNESSE, DICKEY & PIERCE, P.L.C.

By

John A. Castellano, Reg. No. 35,094

P.O. Box 8910  
Reston, VA 20195  
(703) 668-8000

JAC/pw

- ☐ Awaiting Action from Patent Office Examiner  
Expected Date for Action is: \_\_\_\_\_.
- ☐ Awaiting Decision by Board of Appeals.
- ☐ Application allowed on \_\_\_\_\_.
- ☐ Abandoned per \_\_\_\_\_.
- ☐ Other \_\_\_\_\_.